

**Product / Package Information**

Package	LFCSP - Sawn
Body Size (mm)	4 X 4 X 0.75 (2.7 X 3.3 EP)
Lead Count	16
Terminal Finish	100 Sn
MS Number	MS011043C

**Environmental Information**

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

**Materials Declaration**

**Molding Compound**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	1.18E-02	86.91	869100	31.88		318790
Thermosets	Epoxy & Phenol Resin	Proprietary	1.73E-03	12.78	127800	4.69		46878
Other inorganic materials	Carbon black	1333-86-4	4.20E-05	0.31	3100	0.11		1137
Subtotal			1.35 E-02	100.00	1000000	36.68		366805

**Leadframe**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	1.88 E-02	97.5	975000	51.01		510089
Copper & its alloys	Iron	7439-89-6	4.54 E-04	2.35	23500	1.23		12294
Copper & its alloys	Zinc	7440-66-6	2.32 E-05	0.12	1200	0.06		628
Copper & its alloys	Phosphorus	7723-14-0	5.79 E-06	0.03	300	0.02		157
Subtotal			1.93 E-02	100.00	1000000	52.32		523168

**Internal Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	3.97 E-04	100.0	1000000	1.08		10767

**External Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	5.69 E-04	100.0	1000000	1.54		15416

**Bond Wires**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	3.22 E-04	99.0	990000	0.87		8721
Precious metals	Palladium	7440-05-3	3.25 E-06	1.0	10000	0.01		88
Subtotal			3.25 E-04	100.0	1000000	0.88		8809

**Chip**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	2.17 E-03	100.0	1000000	5.87		58728

**Die Attach**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	4.70 E-04	77.71	777100	1.27		12740
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	1.88 E-05	3.11	31100	0.05		510
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	1.88 E-05	3.11	31100	0.05		510
Other organic materials	Butyrolactone, gamma-	96-48-0	1.88 E-05	3.11	31100	0.05		510
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	1.88 E-05	3.11	31100	0.05		510
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	1.88 E-05	3.11	31100	0.05		510
Other organic materials	Organosilane	TS ref# 10001	1.88 E-05	3.11	31100	0.05		510
Other inorganic materials	Copper(II) oxide	1317-38-0	1.88 E-05	3.11	31100	0.05		510
Other organic materials	Epoxy resin modifier	TS ref# 10038	3.15 E-06	0.52	5200	0.009		85
Subtotal			6.05 E-04	100.0	1000000	1.64		16395

<b>Package Totals</b>			<b>Weight (g)</b>	<b>3.69 E-02</b>		<b>Percentage (%)</b>	<b>100</b>	<b>PPM</b>	<b>1000000</b>
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Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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